

31 A, 600 V, very fast IGBT with Ultrafast diode

Features

- Low on-voltage drop ($V_{CE(sat)}$)
- Very soft Ultrafast recovery anti-parallel diode

Applications

- High frequency motor drives
- SMPS and PFC in both hard switch and resonant topologies

Description

This device is an ultrafast IGBT. It utilizes the advanced Power MESH™ process resulting in an excellent trade-off between switching performance and low on-state behavior.

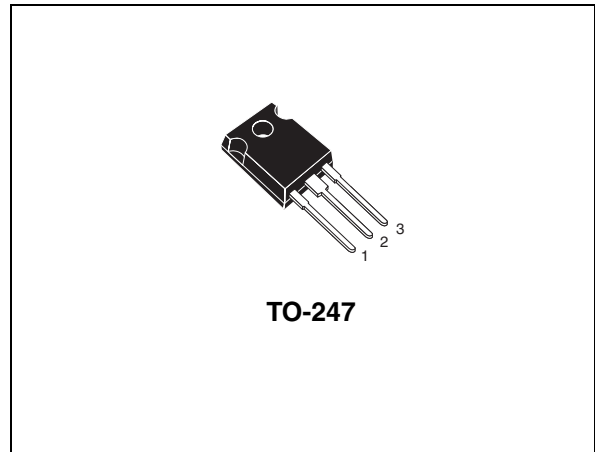


Figure 1. Internal schematic diagram

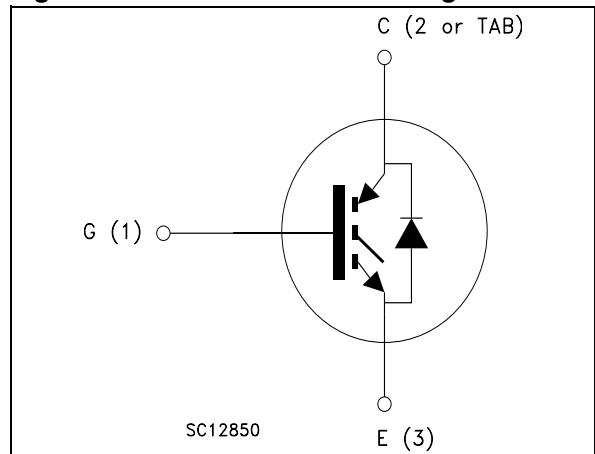


Table 1. Device summary

| Part number | Marking | Package | Packaging |
|---------------|-------------|-------------------|-----------|
| STGWA19NC60HD | GWA19NC60HD | TO-247 long leads | Tube |

Contents

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1 Electrical ratings

Table 2. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|--|-------------|--------------------|
| V_{CES} | Collector-emitter voltage ($V_{GE} = 0$) | 600 | V |
| $I_C^{(1)}$ | Continuous collector current at $T_C = 25\text{ °C}$ | 52 | A |
| $I_C^{(1)}$ | Continuous collector current at $T_C = 100\text{ °C}$ | 31 | A |
| $I_{CL}^{(2)}$ | Turn-off latching current | 40 | A |
| $I_{CP}^{(3)}$ | Pulsed collector current | 60 | A |
| I_F | Diode RMS forward current at $T_C = 25\text{ °C}$ | 20 | A |
| I_{FSM} | Surge not repetitive forward current $t_p=10\text{ ms}$ sinusoidal | 50 | A |
| V_{GE} | Gate-emitter voltage | ± 20 | V |
| P_{TOT} | Total dissipation at $T_C = 25\text{ °C}$ | 208 | W |
| T_J | Operating junction temperature | - 55 to 150 | $^{\circ}\text{C}$ |

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(sat)(\max)}(T_{j(\max)}, I_C(T_C))}$$

2. $V_{clamp} = 80\%V_{CES}$, $T_J = 150\text{ °C}$, $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$

3. Pulse width limited by maximum permissible junction temperature and turn-off within RBSOA

Table 3. Thermal data

| Symbol | Parameter | Value | Unit |
|------------|--|-------|----------------------|
| R_{thJC} | Thermal resistance junction-case IGBT | 0.6 | $^{\circ}\text{C/W}$ |
| | Thermal resistance junction-case diode | 3 | $^{\circ}\text{C/W}$ |
| R_{thJA} | Thermal resistance junction-ambient | 50 | $^{\circ}\text{C/W}$ |

2 Electrical characteristics

$T_J = 25\text{ °C}$ unless otherwise specified)

Table 4. Static

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|----------------|--|--|------|------------------------|-----------|---------------------|
| $V_{(BR)CES}$ | Collector-emitter breakdown voltage ($V_{GE} = 0$) | $I_C = 1\text{ mA}$ | 600 | | | V |
| $V_{CE(sat)}$ | Collector-emitter saturation voltage | $V_{GE} = 15\text{ V}, I_C = 12\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 15\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 30\text{ A}, T_J = 100\text{ °C}$ $V_{GE} = 15\text{ V}, I_C = 12\text{ A}, T_J = 125\text{ °C}$ | | 1.8 2 2.5 1.6 | 2.5 | V |
| $V_{GE(th)}$ | Gate threshold voltage | $V_{CE} = V_{GE}, I_C = 250\text{ }\mu\text{A}$ | 3.75 | | 5.75 | V |
| I_{CES} | Collector cut-off current ($V_{GE} = 0$) | $V_{CE} = 600\text{ V}$ $V_{CE} = 600\text{ V}, T_J = 125\text{ °C}$ | | | 150 1 | μA mA |
| I_{GES} | Gate-emitter leakage current ($V_{CE} = 0$) | $V_{GE} = \pm 20\text{ V}$ | | | ± 100 | nA |
| $g_{fs}^{(1)}$ | Forward transconductance | $V_{CE} = 15\text{ V}, I_C = 12\text{ A}$ | | 5 | | S |

1. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------|------------------------------|--|------|------|------|------|
| C_{ies} | Input capacitance | | | 1180 | | pF |
| C_{oes} | Output capacitance | $V_{CE} = 25\text{ V}, f = 1\text{ MHz},$ | - | 130 | - | pF |
| C_{res} | Reverse transfer capacitance | $V_{GE} = 0$ | | 36 | | pF |
| Q_g | Total gate charge | $V_{CE} = 390\text{ V}, I_C = 5\text{ A},$ | | 53 | | nC |
| Q_{ge} | Gate-emitter charge | $V_{GE} = 15\text{ V},$ | - | 10 | - | nC |
| Q_{gc} | Gate-collector charge | Figure 18 | | 23 | | nC |

Table 6. Switching on/off (inductive load)

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---|---|---|------|------------------|------|------------------------|
| $t_{d(on)}$ t_r $(di/dt)_{on}$ | Turn-on delay time Current rise time Turn-on current slope | $V_{CC} = 390\text{ V}$, $I_C = 12\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, <i>Figure 19</i> | - | 25 7 1600 | - | ns ns A/ μ s |
| $t_{d(on)}$ t_r $(di/dt)_{on}$ | Turn-on delay time Current rise time Turn-on current slope | $V_{CC} = 390\text{ V}$, $I_C = 12\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$ <i>Figure 19</i> | - | 24 8 1400 | - | ns ns A/ μ s |
| $t_{r(Voff)}$ $t_{d(Voff)}$ t_f | Off voltage rise time Turn-off delay time Current fall time | $V_{CC} = 390\text{ V}$, $I_C = 12\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, <i>Figure 19</i> | - | 27 97 73 | - | ns ns ns |
| $t_{r(Voff)}$ $t_{d(Voff)}$ t_f | Off voltage rise time Turn-off delay time Current fall time | $V_{CC} = 390\text{ V}$, $I_C = 12\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$ <i>Figure 19</i> | - | 58 144 128 | - | ns ns ns |

Table 7. Switching energy (inductive load)

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---|---|---|------|-------------------|------|-------------------------------|
| E_{on} $E_{off}^{(1)}$ E_{ts} | Turn-on switching losses Turn-off switching losses Total switching losses | $V_{CC} = 390\text{ V}$, $I_C = 12\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, <i>Figure 19</i> | - | 85 189 274 | - | μ J μ J μ J |
| E_{on} $E_{off}^{(1)}$ E_{ts} | Turn-on switching losses Turn-off switching losses Total switching losses | $V_{CC} = 390\text{ V}$, $I_C = 12\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$ <i>Figure 19</i> | - | 187 407 594 | - | μ J μ J μ J |

1. Turn-off losses include also the tail of the collector current

Table 8. Collector-emitter diode

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|--|---|------|----------------|------|---------------|
| V_F | Forward on-voltage | $I_F = 12\text{ A}$ $I_F = 12\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$ | - | 2.6 2.1 | - | V V |
| t_{rr} Q_{rr} I_{rrm} | Reverse recovery time Reverse recovery charge Reverse recovery current | $I_F = 12\text{ A}$, $V_R = 40\text{ V}$, $di/dt = 100\text{ A}/\mu\text{s}$ <i>Figure 20</i> | - | 31 30 2 | - | ns nC A |
| t_{rr} Q_{rr} I_{rrm} | Reverse recovery time Reverse recovery charge Reverse recovery current | $I_F = 12\text{ A}$, $V_R = 40\text{ V}$, $T_J = 125\text{ }^\circ\text{C}$, $di/dt = 100\text{ A}/\mu\text{s}$ <i>Figure 20</i> | - | 59 102 4 | - | ns nC A |

2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

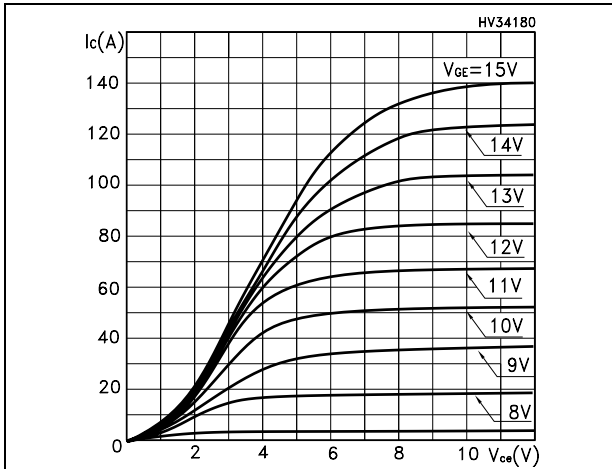


Figure 3. Transfer characteristics

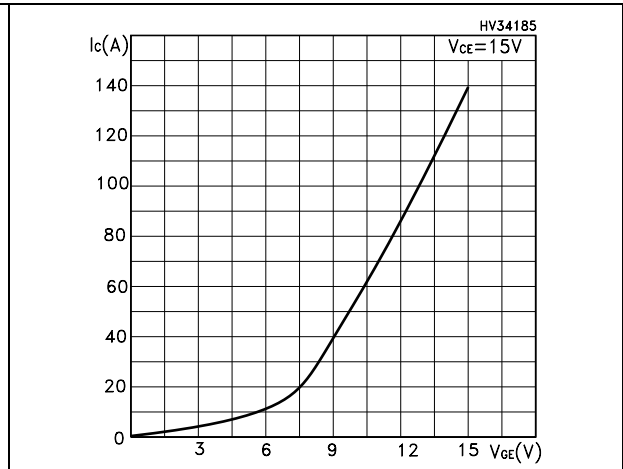


Figure 4. Transconductance

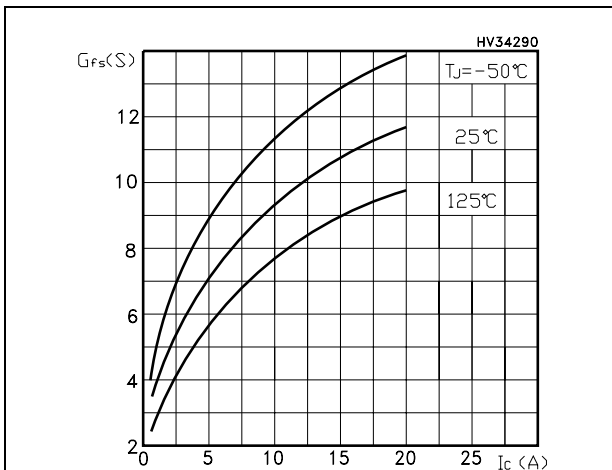


Figure 5. Collector-emitter on voltage vs. temperature

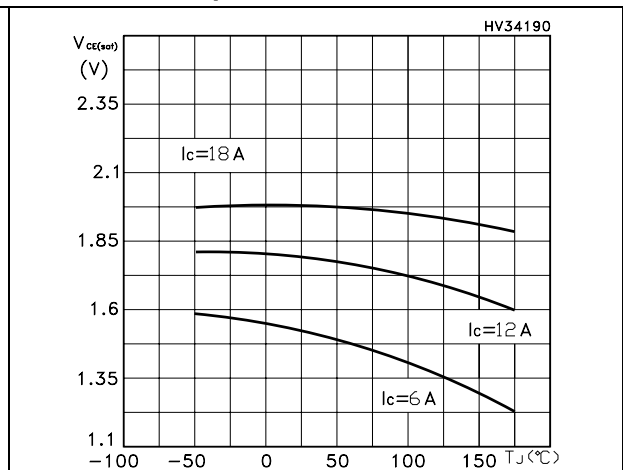


Figure 6. Gate charge vs. gate-source voltage

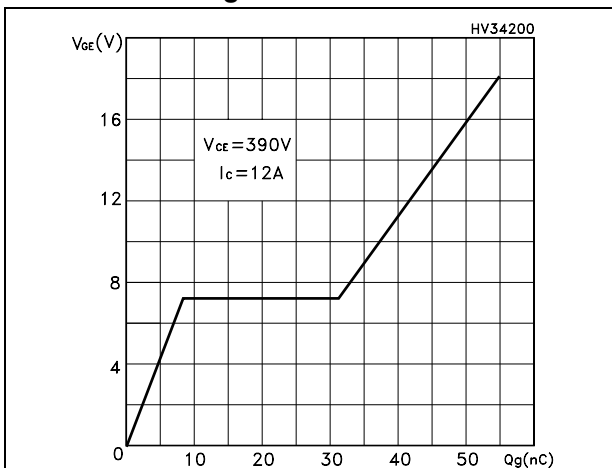


Figure 7. Capacitance variations

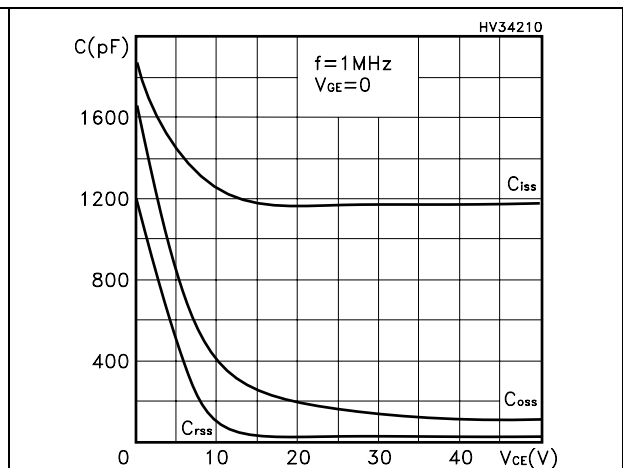


Figure 8. Normalized gate threshold voltage vs. temperature

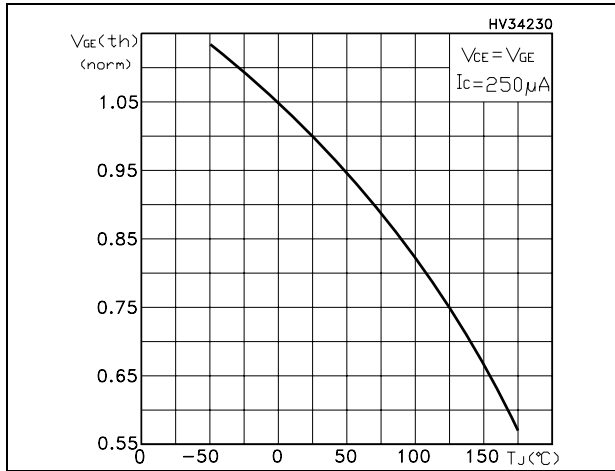


Figure 9. Collector-emitter on voltage vs. collector current

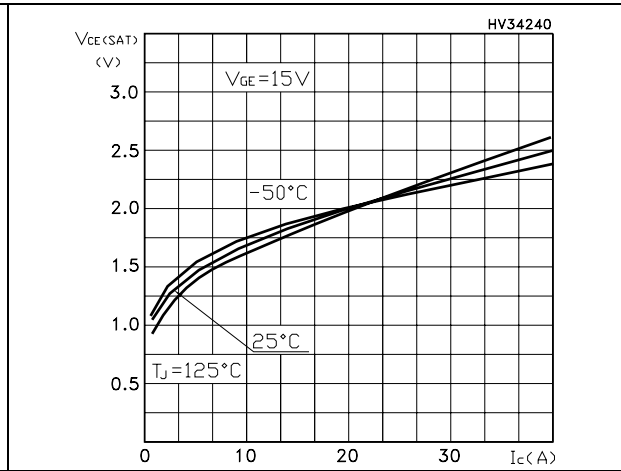


Figure 10. Normalized breakdown voltage vs. temperature

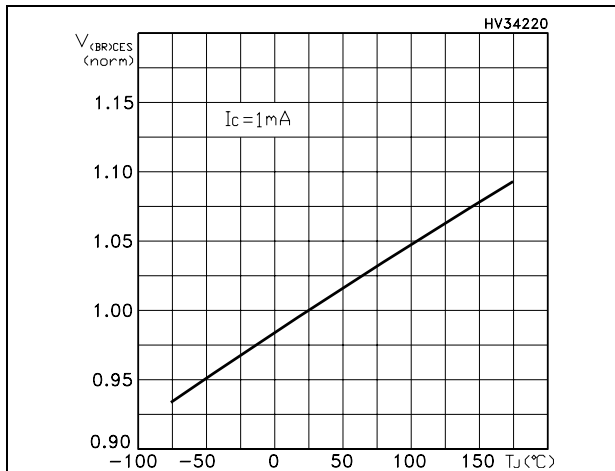


Figure 11. Switching losses vs. temperature

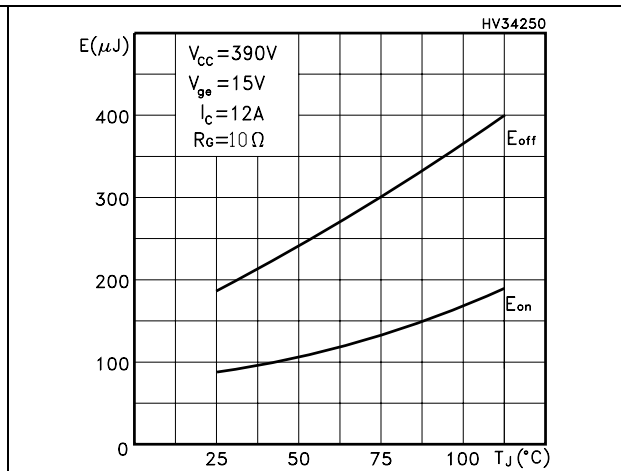


Figure 12. Switching losses vs. gate resistance

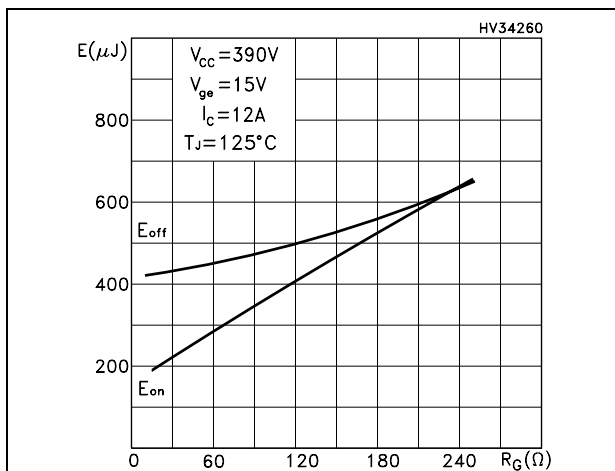


Figure 13. Switching losses vs. collector current

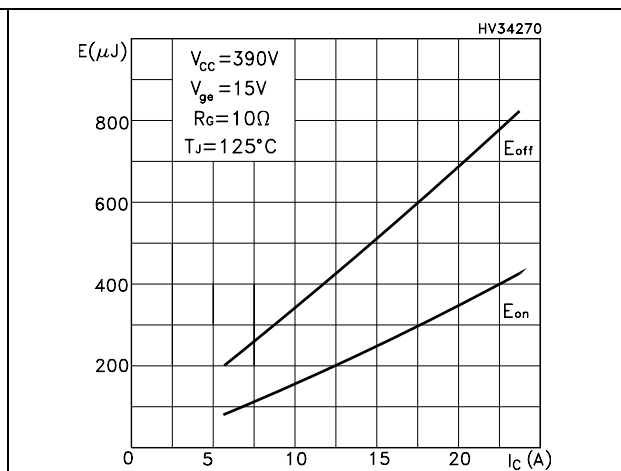


Figure 14. Turn-off SOA

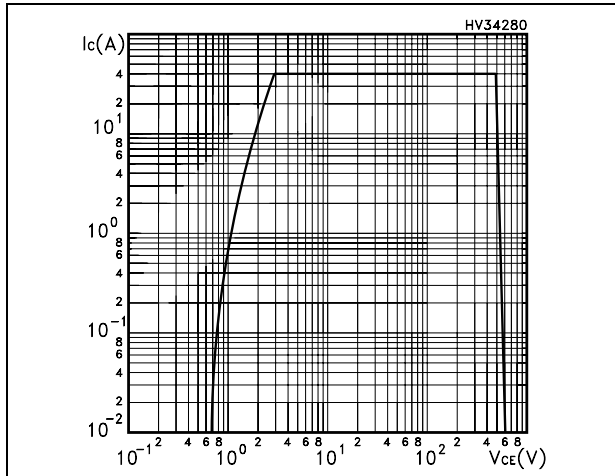


Figure 15. Thermal impedance

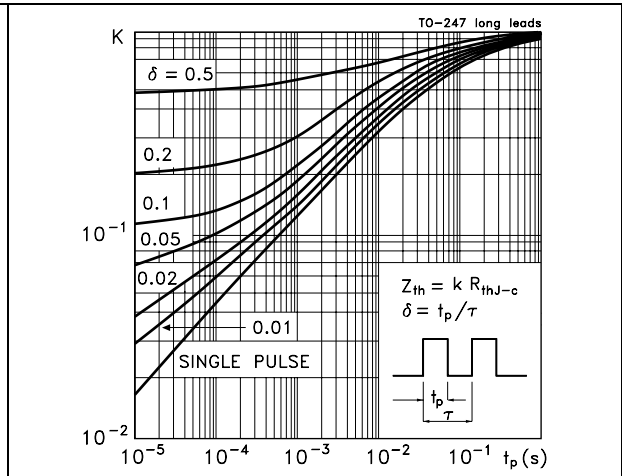
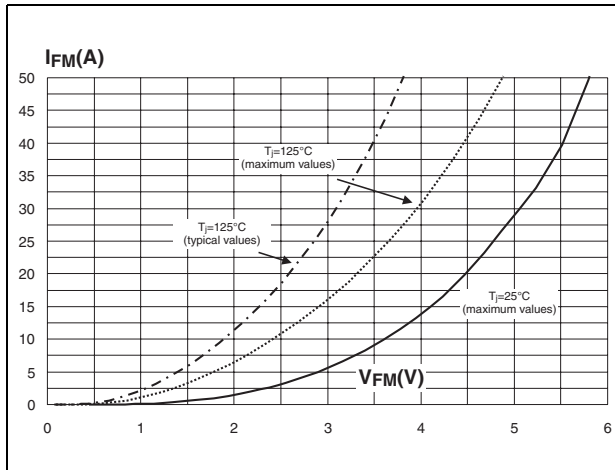
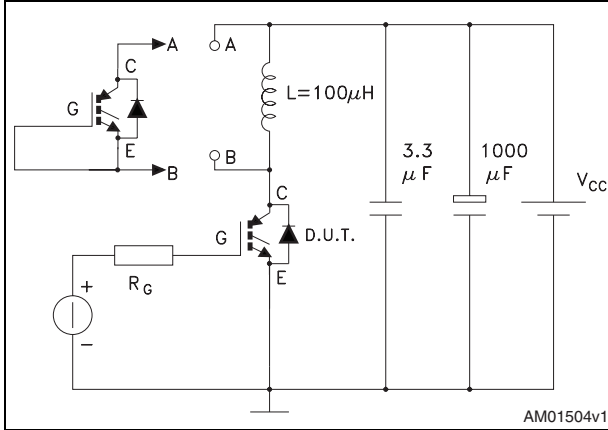


Figure 16. Forward voltage drop vs. forward current



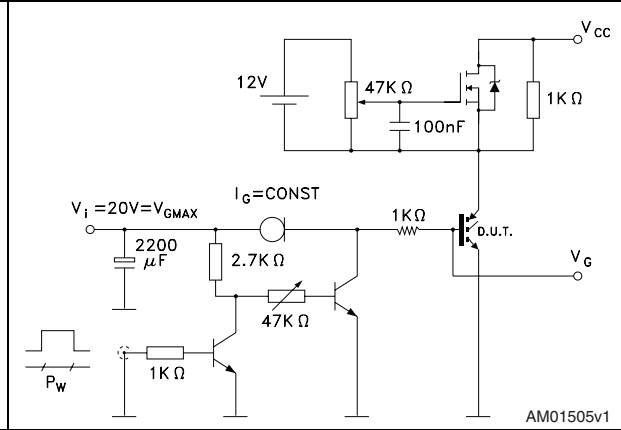
3 Test circuits

Figure 17. Test circuit for inductive load switching



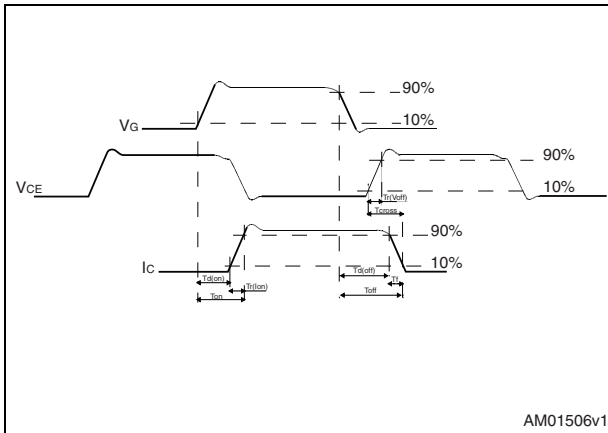
AM01504v1

Figure 18. Gate charge test circuit



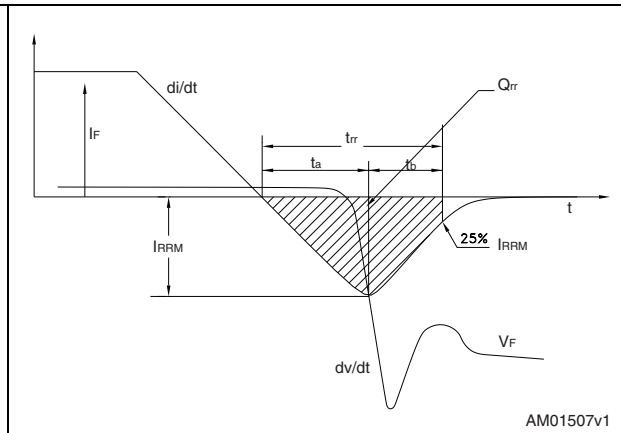
AM01505v1

Figure 19. Switching waveform



AM01506v1

Figure 20. Diode recovery time waveform



AM01507v1

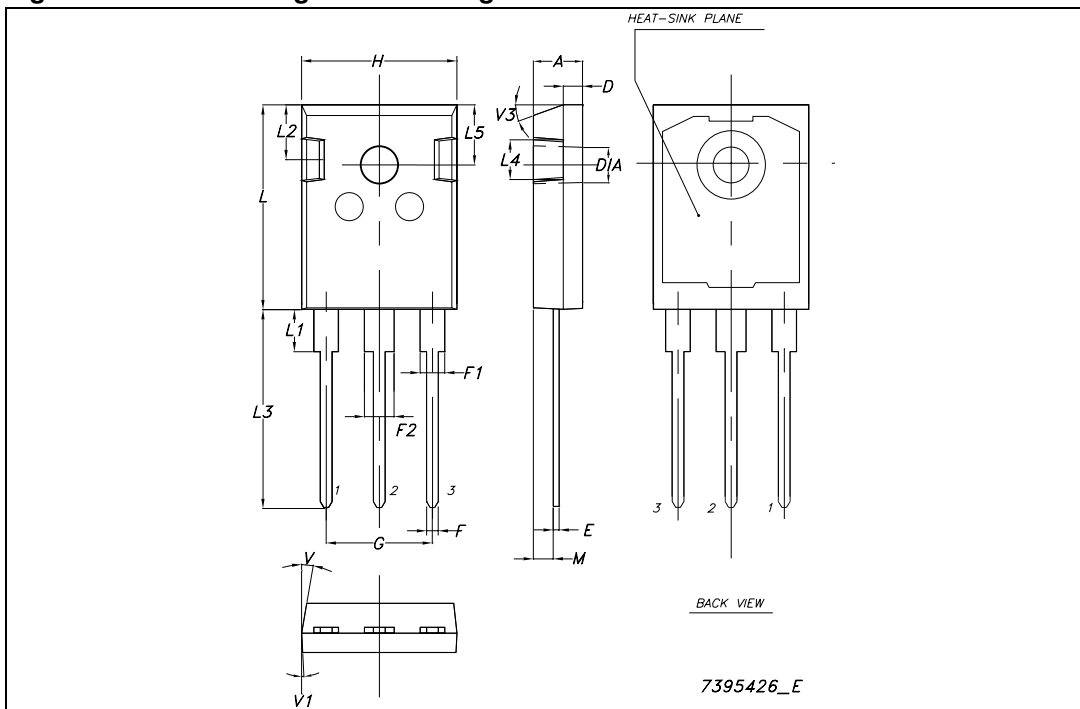
4 Package mechanical data

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Table 9. TO-247 long leads mechanical data

| Dim. | mm. | | |
|------|-----------|------|-------|
| | Min. | Typ. | Max. |
| A | 4.90 | | 5.15 |
| D | 1.85 | | 2.10 |
| E | 0.55 | | 0.67 |
| F | 1.07 | | 1.32 |
| F1 | 1.90 | | 2.38 |
| F2 | 2.87 | | 3.38 |
| G | 10.90 BSC | | |
| H | 15.77 | | 16.02 |
| L | 20.82 | | 21.07 |
| L1 | 4.16 | | 4.47 |
| L2 | 5.49 | | 5.74 |
| L3 | 20.05 | | 20.30 |
| L4 | 3.68 | | 3.93 |
| L5 | 6.04 | | 6.29 |
| M | 2.27 | | 2.52 |
| V | | 10° | |
| V1 | | 3° | |
| V3 | | 20° | |
| Dia. | 3.55 | | 3.66 |

Figure 21. TO-247 long leads drawing



5 Revision history

Table 10. Document revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 14-Sep-2011 | 1 | Initial release. |

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- Оценку стоимости проекта по компонентам.
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